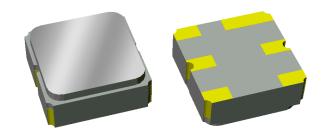


# **Applications**

- For filtering in DPD path
- For ultra wideband applications
- Wireless infrastructure



### **Product Features**

- Usable bandwidth 160 MHz
- Low Loss
- High attenuation,
- Excellent power handling
- Single-ended operation
- Matching required for operation at  $50\Omega$
- Small Size: 3.00 x 3.00 x 1.22 mm
- Ceramic Surface Mount Package (SMP)
- Hermetically sealed
- RoHS compliant, Pb-free



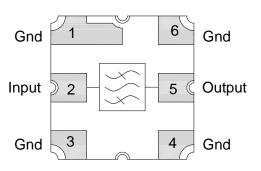
### **General Description**

857145 is a RF filter for wireless infrastructure applications. This filter was specifically designed for filtering in the digital pre-distortion path in Base Station applications. This filter is designed in a 3x3mm hermetic package and is part of our wide portfolio of RF filters in the same package.

Low insertion loss, coupled with high attenuation and excellent power handling, makes this filter a natural choice for our customers Downlink RF filtering needs.

### **Functional Block Diagram**

Top view



# Pin Configuration

Pin # SE	Description
2	Input
5	Output
1,3,4,6	Case Ground

# Ordering Information

Part No.	Description
857145	packaged part
857145-EVB	evaluation board

Standard T/R size = 5000 units/reel.

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# **Specifications**

# Electrical Specifications (1)

Specified Temperature Range: (2) -40 to +85 °C

Parameter (3)	Conditions	Min	Typical (4)	Max	Units
Center Frequency		-	1960	-	MHz
Maximum Insertion Loss	1930 – 1990 MHz	-	3.0	4.0	dB
Amplitude Variation (5)	1930 – 1990 MHz	-	0.7	1.1	dB p-p
	1930 – 1990 MHz (Over any 5 MHz span)	-	0.3	0.6	dB p-p
	1880 – 2040 MHz	-	1.5	2.5	dB p-p
Phase Ripple (5)	1930 – 1990 MHz	-	2.6	6	deg p-p
	1930 – 1990 MHz (Over any 5 MHz span)	-	1.7	3	deg p-p
	1880 – 2040 MHz	-	21	36	deg p-p
Group Delay Variation (5)	1930 – 1990 MHz	-	2.8	6	ns p-p
	1880 – 2040 MHz	-	6.2	12	ns p-p
Absolute Delay	Average over 1930 – 1990 MHz	-	4	10	ns
EVM	1930 – 1990 MHz (Over any 3.84 MHz	-	0.8	1.5	%
	span)				
IIP3 <sup>(6)</sup>	Tones 5 MHz separated, power > 5dBm per	44	52	-	dBm
	tone				-
Temperature Drift (7)	1930 – 1990 MHz	-	0.22	0.3	dB
Input/Output VSWR	1930 – 1990 MHz	-	1.5	2.0:1	-
Relative Attenuation (8)	10 – 704 MHz	45	53	-	dB
	704 – 1561 MHz	25	29	-	dB
	1561 – 1622 MHz	25	29	-	dB
	1622 – 1790 MHz	25	29	-	dB
	2170 – 4000 MHz	25	28	-	dB
	4000 – 6000 MHz	20	25	-	dB
Source/Load Impedance (9)	Single-ended	-	50	-	Ω

#### Notes:

- 1. All specifications are based on the TriQuint schematic shown on page 3.
- 2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature.
- 3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances.
- 4. Typical values are based on average measurements at room temperature.
- 5. Variation is defined as the total peak to peak variation over the defined frequency range.
- 6. To be measured only during engineering development.
- 7. Temperature Drift specification is defined on Page 3 and is guaranteed by design and won't be measured in production
- 8. Relative to maximum insertion loss at center frequency.
- 9. This is the optimum impedance in order to achieve the performance shown.

# **Absolute Maximum Ratings**

Parameter	Rating
Operable Temperature	-40 to +85 °C
Storage Temperature	-40 to +85 °C
Input Power	+22 dBm (max) CW for 24 hours at +55°C

Operation of this device outside the parameter ranges given above may cause permanent damage.



## **Temperature Drift Specification**

Temperature Drift Equations:

$$\mbox{Temp Drift}_{high} = \mid \frac{max(T_{ambient} - T_{hot}) \, - \, min(T_{ambient} - \, T_{hot})}{2} \mid$$

$$Temp\ Drift\ _{low} = \ \mid \frac{max(T_{ambient} - T_{cold})\ -\ min(T_{ambient} -\ T_{cold})}{2} \mid$$

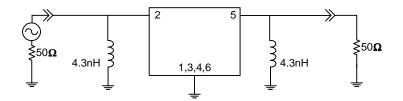
Temperature Drift Terms Defined:

 $T_{ambient}$  - Transmission power in dB measured at +25 degrees C.  $T_{hot}$  - Transmission power in dB measured at +85 degrees C.  $T_{cold}$  - Transmission power in dB measured at -40 degrees C. Temperature Drift - Greater of Temp Drift  $_{high}$  vs Temp Drift  $_{low}$ 

## Reference Design

### **Schematic**

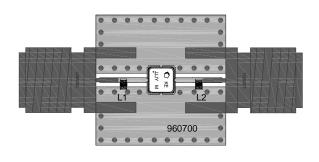


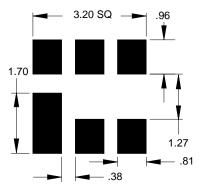


 $\begin{array}{c} 50\,\Omega\\ Single-ended\\ Output \end{array}$ 

### **PC Board**

# **Mounting Configuration**





Notes:

Top, middle & bottom layers: 1 oz copper Substrates: FR4 dielectric, .031" thick

Finish plating: Nickel: 3-8µm thick, Gold: .03-.2µm thick

Hole plating: Copper min .0008µm thick

#### Notes:

- 1. All dimensions are in millimeters.
- 2. This footprint represents a recommendation only.

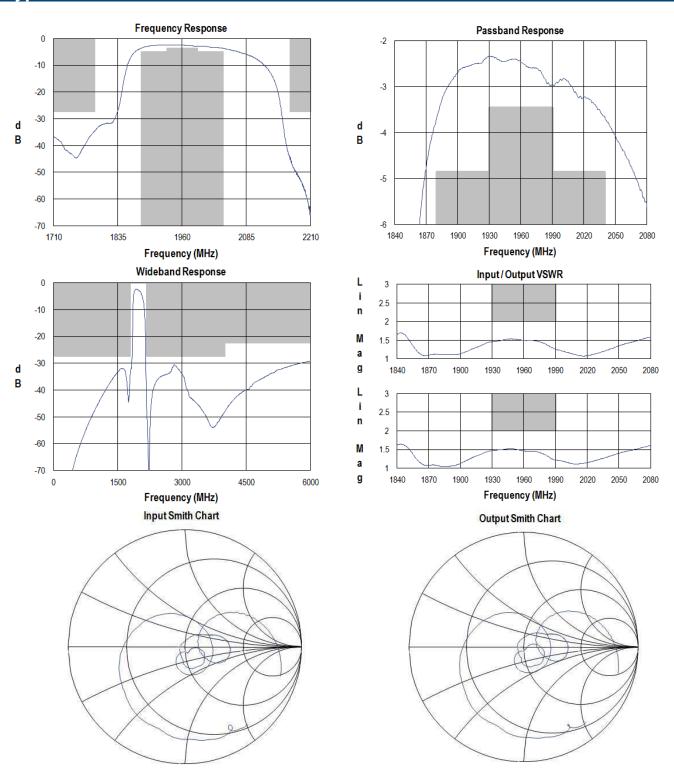
#### **Bill of Material**

Reference Desg.	Value	Description	Manufacturer	Part Number
L1	4.3nH	Coil Wire-wound, 0402, 5%	MuRata	LQW15AN4N3D00
L2	4.3nH	Coil Wire-wound, 0402, 5%	MuRata	LQW15AN4N3D00
SMA	N/A	SMA connector	Radiall USA Inc.	9602-1111-018
PCB	N/A	3-layer	multiple	960700

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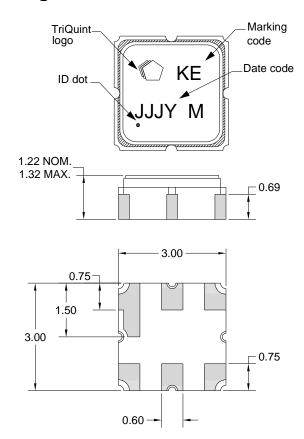
# Typical Performance (at room temperature)





### **Mechanical Information**

### **Package Information, Dimensions and Marking**



Package Style: SMP-12A

Dimensions: 3.00 x 3.00 x 1.22 mm

Body:  $Al_2O_3$  ceramic Lid: Kovar, Ni plated

Terminations: Au plating 0.5 - 1.0 $\mu$ m, over a 2-6 $\mu$ m Ni

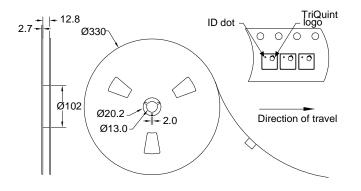
plating

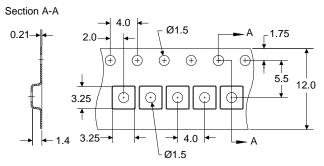
All dimensions shown are nominal in millimeters All tolerances are  $\pm 0.15 mm$  except overall length and width  $\pm 0.10 mm$ 

The date code consists of day of the current year (Julian, 3 digits),  $Y = last\ digit\ of\ the\ year,\ and\ M = manufacturing\ site\ code$ 

# **Tape and Reel Information**

Standard T/R size = 5000 units/reel. All dimensions are in millimeters







### **Product Compliance Information**

#### **ESD Information**



### **Caution! ESD-Sensitive Device**

ESD Rating: 1B

Value: Passes ≥ 550 V min.
Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-A114

ESD Rating: B

Value: Passes  $\geq 200 \text{ V min.}$ Test: Machine Model (MM)

Standard: JEDEC Standard JESD22-A115

## **MSL Rating**

Devices are Hermetic, therefore MSL is not applicable

# **Solderability**

Compatible with the latest version of J-STD-020, lead free solder,  $260^{\circ}\text{C}$ 

Refer to **Soldering Profile** for recommended guidelines.

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A  $(C_{15}H_{12}Br_4O_2)$  Free
- PFOS Free
- SVHC Free

### **Contact Information**

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